

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



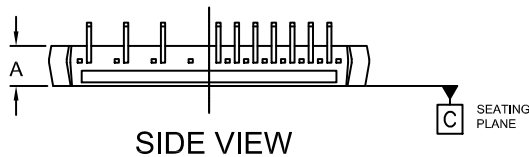
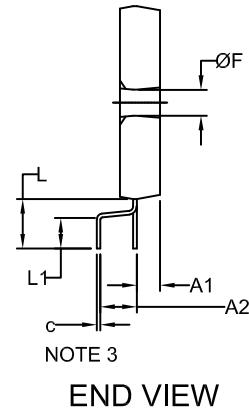
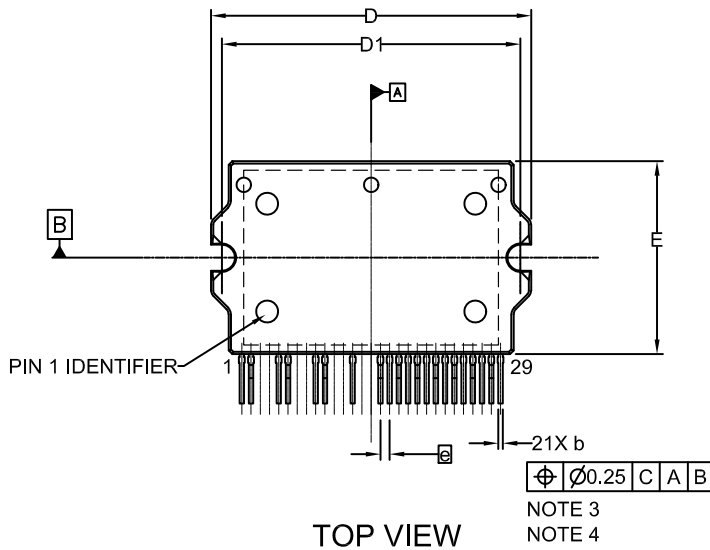
SIP29 44x26.5
CASE 127ET
ISSUE O

DATE 18 AUG 2017

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b and c APPLY TO THE PLATED LEADS AND ARE MEASURED BETWEEN 1.00 AND 2.00 FROM THE LEAD TIP.
4. POSITION OF THE LEAD IS DETERMINED AT THE ROOT OF THE LEAD WHERE IT EXITS THE PACKAGE BODY.
5. PIN 1 IDENTIFICATION IS A MIRRORRED SURFACE INDENT.
6. MISSING PINS ARE 3,4,7,8,11,12,14 AND 15.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	5.00	5.50	6.00
A1	2.70	3.20	3.70
A2	4.50	5.00	5.50
b	0.55	0.60	0.65
c	0.45	0.50	0.55
D	43.50	44.00	44.50
D1	40.50	41.00	41.50
E	26.00	26.50	27.00
e	1.27 BSC		
F	3.10	3.60	4.10
L	6.30	6.80	7.30
L1	3.80	4.30	4.80



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SIP29 44X26.5	PAGE 1 OF 2

